

COLD MOUNTING CONSUMABLES



MLP-CM1

Code	Description	Package
MLP-CM1	<ol style="list-style-type: none"> 1. fast curing speed, good transparency, low viscosity, high strength 2. for metallographic samples without heating, pressure and mounting 3. curing time: 25°C, 25min 4. usage: mix cold mounting resin and curing liquid at 10:8 	cold mounting resin: 1000g curing agent: 800mL
MLP-CM3	<ol style="list-style-type: none"> 1. fast curing speed, good transparency 2. for samples which can not be heated, like PCB,SMT and other micro-slice samples 3. curing time: 25°C, 1h 4. usage: mix resin liquid and curing liquid at 2:1 	resin liquid: 1000mL curing agent: 500mL
MLP-CM4	<ol style="list-style-type: none"> 1. low viscosity, good permeability, high transparency. 2. for samples which can not be heated, like PCB,SMT and other micro-slice samples 3. curing time: 25°C, 3~4h 4. usage: mix resin liquid and curing liquid at 2:1 	resin liquid: 1000mL curing agent: 500mL
MLP-CM5	<ol style="list-style-type: none"> 1. low heat generation, low shrinkage, high permeability, high transparency 2. for temperature-sensitive samples, like PCB,SMT and other micro-slice samples 3. curing time: 25°C, 20~24h 4. usage: mix resin liquid and curing liquid at 3:1 	resin liquid: 1000mL curing agent: 300mL
MLP-CM7	<ol style="list-style-type: none"> 1. UV curing adhesive, high transparency, good fluidity 2. for scenarios that require rapid embedding, like PCB,SMT and other micro-slice samples 3. curing time: used with light curing machine, curing time less than 10min 4. usage: use directly 	UV adhesive: 1000mL